



P.C.B. LAYOUT

P/N	Contact	Dim A	Dim B	Dim C	Dim D	P/N	Contact	Dim A	Dim B	Dim C	Dim D
SE0630X0X	6	7.62	5.08	7.62	10.16	SE3240X0X	32	40.64	38.10	10.16	12.70
SE0830X0X	8	10.16	7.62	7.62	10.16	SE2460X0X	24	30.48	27.94	15.24	17.78
SE1030X0X	10	12.70	10.16	7.62	10.16	SE2860X0X	28	35.56	33.02	15.24	17.78
SE1430X0X	14	17.78	15.24	7.62	10.16	SE3260X0X	32	40.64	38.10	15.24	17.78
SE1630X0X	16	20.32	17.78	7.62	10.16	SE3660X0X	36	45.72	43.18	15.24	17.78
SE1830X0X	18	22.86	20.32	7.62	10.16	SE4060X0X	40	50.80	48.26	15.24	17.78
SE2030X0X	20	25.40	22.86	7.62	10.16	SE4260X0X	42	53.34	50.80	15.24	17.78
SE2430X0X	24	30.48	27.94	7.62	10.16	SE4860X0X	48	60.96	58.42	15.24	17.78
SE2830X0X	28	35.56	33.02	7.62	10.16	SE5060X0X	50	63.50	60.96	15.24	17.78
SE2040X0X	20	25.40	22.86	10.16	12.70	SE5260X0X	52	66.04	63.50	15.24	17.78
SE2240X0X	22	27.94	25.40	10.16	12.70	SE5090X0X	50	63.50	60.96	22.86	25.40
SE2440X0X	24	30.48	27.94	10.16	12.70	SE5290X0X	52	66.04	63.50	22.86	25.40
SE2840X0X	28	35.56	33.02	10.16	12.70	SE6490X0X	64	81.28	78.74	22.86	25.40

SIGN	DATE	DESCRIPTION	APPROVER
△			

THIS IS CAD DRAWING, DO NOT REVISE MANUALLY!!!

Technical Data

- Material:
 - Pin (outer sleeve) : Brass,machined, CuZn38Pb2
 - Clip(contact 4 finger) : Beryllium copper ,heat treated or PHBZ
 - Plating(outer sleeve) : Tin plated : 2um/80u"nickel,5um/200u"Tin
 - Gold plated: 2um/80u"nickel,full gold
 - 2um/80 u"nickel,gold or tin plating
- Plating clip(contact):
- Insulator body(black) : Glass filled Hi-temperature thermoplastic UL94V-0

- Electrical
 - Current rating : 3 Amps/contact max.
 - Contact resistance : ≤4mΩ/contact
 - Insulation resistance : ≥10000MΩat 500VAC
 - Rated voltage : 100 VRMS /150VDC

- Mechanical
 - Operating temperature : Gold plated:-55°C to +125°C
 - (Continuous) -67°F to +105°F
 - Tin plated:-40°C to +105°C

Average insertion force with steel pin of: Ø0.43mm/0.017" < 250g
 Average withdrawal force with steel pin of Ø0.43mm/0.017" >50g
 Mechanical life : min.200

Applications and features:

- The open frame is most common type.
- The open body design gives better access (for cleaning and inspections) to air -cooling.
- Side and end stackable.
- High retention design prevents IC walkout during heavy vibration.
- Closed bottom sleeve for 100% anti-wicking of solder.
- Twist free construction.

Environmental data

Solderability (IEC 60068-2-20. Ta) :235°C, 2s
 Resistance to soldering heat (IEC 60068-2-20. Tb) :
 -Through hole mount components :260°C, 10s

SE - XX X 0 X 0 0100G

No.of contacts :06p ~64p

Code	Definition	Clip plated	Pin plated
0	7.62/.300"	Gold Flash	Tin 200u"
1	10.16/.400"	Gold 10u"	Tin 200u"
2	15.24/.600"	Gold 30u"	Tin 200u"
3	22.86/.900"	Tin 200u"	Tin 200u"
4		Gold flash	Gold flash
5		Gold 10u"	Gold flash
6		Gold 30u"	Gold flash

ANYTEK

CUSTOMER COPY

ALL RIGHTS RESERVED. REPRODUCTION OR ISSUE TO THIRD PARTIES IN ANY FORM WHATSOEVER IS NOT PERMITTED WITHOUT WRITTEN AUTHORITY FROM THE PROPRIETOR. PROPERTY OF ANYTEK TECHNOLOGY CO., LTD

TITLE		IC/SKT SE 4.2 mL finished products series (Open frame) ROHS					
PART NO.	SEXXX0X00100G			DWG NO.	8SE0301-42		
APPROVED	CHECKED	DESIGNED	DRAWN	CUST NO.	Tolerance		
		Seamus 2005.09.20	Aaron 2005.08.01		UNIT: mm SCALE: NONE SHEET: 01/01	X. ±0.50 X.X ±0.30 X.XX ±0.10 X* ±1*	